PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2725328

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JINRONG YE	10/17/2012

RECEIVING PARTY DATA

Name:	Hangzhou H3C Technologies Co., Ltd.
Street Address:	Huawei Hangzhou Manufacturing Base, 310 Liuhe Road, Zhijiang Hi-Tech Park
Internal Address:	Hangzhou Hi-Tech Industry Development Zone
City:	Hangzhou, Zhejiang
State/Country:	CHINA
Postal Code:	310053

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14238707

CORRESPONDENCE DATA

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Signature:	/Ashok K. Mannava/
Date:	02/12/2014

Total Attachments: 1
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HEWLETT-PACKARD COMPANY
Intellectual Property Administrator
3404 E. Harmony Road
Mail Stop 35
Fort Collins, Colorado 80528

PATENT APPLICATION

RECORD ID: 82972108

ASSIGNMENT OF PATENT APPLICATION

I/We, the undersigned (each) have agreed and hereby agree to assign to Hangzhou H3C Technologies Co., Ltd., a company having its principal place of business at Huawei Hangzhou Manufacturing Base, 310 Liuhe Road, Zhijiang Hi-Tech Park, Hangzhou Hi-Tech Industry Development Zone, Hangzhou, Zhejiang 310053, the People's Republic of China, (hereinafter H3C), in furtherance of my/our obligations to H3C and its subsidiaries and affiliates, and do hereby assign and transfer to H3C, its successors and assigns, the entire right, title and interest, including the right of priority, in, to and under an application for Letters Patent of the United States entitled:

Notifying Of A LSP Failure

Filing Date: February 12, 2014 **Application No.:** 14/238,707

and the invention(s) and improvement(s) set forth therein, and any and all continuations, continuations-in-part (C-I-P's), divisionals, and renewals of and substitutes for said application for said Letters Patent, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefore; and any reissues, or reexaminations, or extensions of said Letters Patent.

I/we additionally authorize H3C to file applications in my/our name for Letters Patent in any country, to be held and enjoyed by H3C, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Letters Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me/us had this assignment, and transfer not been made;

AND I/we hereby covenant that I/we have full right to convey the entire interest herein assigned, and that I/we have not executed and will not execute any agreement in conflict herewith, and I/we further covenant and agree that I/we will, each time a request is made, and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said invention(s) or improvement(s), said application and said Letters Patent, to H3C, its successors, assigns, nominees or legal representatives, and I/we agree to communicate to H3C, or to its nominee, all known facts respecting said invention(s) or improvement(s), said application and said Letters Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisionals, continuations, C-I-P's, reissue and foreign applications, to make all rightful oaths and declarations, and generally to do everything possible to aid H3C, its successors, assigns, nominees and legal representatives to obtain and enforce, for its or their own benefit, proper patent protection for said invention(s) or improvement(s) in any and all countries provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by H3C;

AND I/we hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any country or countries foreign to the United States whose duty it is to issue patents on applications as aforesaid, to issue to H3C, as assignee of the entire right, title and interest, any and all Letters Patent for said invention(s) or improvement(s), including any and all Letters Patent of the United States which may be issued and granted on or as a result of the application aforesaid, in accordance with the terms of this assignment.

I/we further authorize and direct the attorneys of record to insert the serial number and filing date of said application now identified by the Record ID and title set forth above as soon as the same shall have been made known to them by the United States Patent and Trademark Office.

Jinrong Ye Inventor's Signature	2012.10.17 Date Assignment Signed
Jinrong Ye Inventor's Typed Name	2012.10.17 Date Application Signed
Inventor's Signature	Date Assignment Signed
Inventor's Typed Name	Date Application Signed